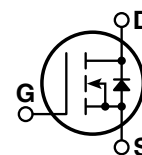
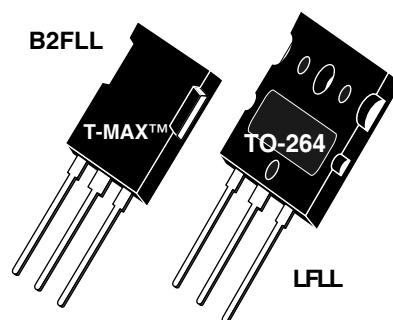


## POWER MOS 7® FREDFET

Power MOS 7® is a new generation of low loss, high voltage, N-Channel enhancement mode power MOSFETS. Both conduction and switching losses are addressed with Power MOS 7® by significantly lowering  $R_{DS(ON)}$  and  $Q_g$ . Power MOS 7® combines lower conduction and switching losses along with exceptionally fast switching speeds inherent with APT's patented metal gate structure.

- Lower Input Capacitance
- Lower Miller Capacitance
- Lower Gate Charge,  $Q_g$
- Increased Power Dissipation
- Easier To Drive
- Popular T-MAX™ or TO-264 Package
- **FAST RECOVERY BODY DIODE**




### MAXIMUM RATINGS

All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	APT20M16B2FLL_LFLL	UNIT
$V_{DSS}$	Drain-Source Voltage	200	Volts
$I_D$	Continuous Drain Current <sup>⑦</sup> @ $T_C = 25^\circ\text{C}$	100	Amps
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	400	
$V_{GS}$	Gate-Source Voltage Continuous	$\pm 30$	Volts
$V_{GSM}$	Gate-Source Voltage Transient	$\pm 40$	
$P_D$	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	694	Watts
	Linear Derating Factor	5.56	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$T_L$	Lead Temperature: 0.063" from Case for 10 Sec.	300	
$I_{AR}$	Avalanche Current <sup>①</sup> (Repetitive and Non-Repetitive)	100	Amps
$E_{AR}$	Repetitive Avalanche Energy <sup>①</sup>	50	mJ
$E_{AS}$	Single Pulse Avalanche Energy <sup>④</sup>	3000	

### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$BV_{DSS}$	Drain-Source Breakdown Voltage ( $V_{GS} = 0\text{V}$ , $I_D = 250\mu\text{A}$ )	200			Volts
$R_{DS(on)}$	Drain-Source On-State Resistance <sup>②</sup> ( $V_{GS} = 10\text{V}$ , $I_D = 50\text{A}$ )			0.016	Ohms
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{DS} = 200\text{V}$ , $V_{GS} = 0\text{V}$ )			250	$\mu\text{A}$
	Zero Gate Voltage Drain Current ( $V_{DS} = 160\text{V}$ , $V_{GS} = 0\text{V}$ , $T_C = 125^\circ\text{C}$ )			1000	
$I_{GSS}$	Gate-Source Leakage Current ( $V_{GS} = \pm 30\text{V}$ , $V_{DS} = 0\text{V}$ )			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage ( $V_{DS} = V_{GS}$ , $I_D = 2.5\text{mA}$ )	3		5	Volts

 **CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - <http://www.advancedpower.com>

**DYNAMIC CHARACTERISTICS**

**APT20M16B2FLL\_LFLL**

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
$C_{iss}$	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{ MHz}$		7220		pF
$C_{oss}$	Output Capacitance			2330		
$C_{rss}$	Reverse Transfer Capacitance			145		
$Q_g$	Total Gate Charge ③	$V_{GS} = 10V$ $V_{DD} = 100V$ $I_D = 100A @ 25^\circ C$		140		nC
$Q_{gs}$	Gate-Source Charge			65		
$Q_{gd}$	Gate-Drain ("Miller") Charge			120		
$t_{d(on)}$	Turn-on Delay Time	<b>RESISTIVE SWITCHING</b> $V_{GS} = 15V$ $V_{DD} = 100V$ $I_D = 100A @ 25^\circ C$ $R_G = 0.6\Omega$		15		ns
$t_r$	Rise Time			31		
$t_{d(off)}$	Turn-off Delay Time			29		
$t_f$	Fall Time			4		
$E_{on}$	Turn-on Switching Energy ⑥	<b>INDUCTIVE SWITCHING @ 25^\circ C</b> $V_{DD} = 133V, V_{GS} = 15V$ $I_D = 100A, R_G = 5\Omega$		850		$\mu J$
$E_{off}$	Turn-off Switching Energy			930		
$E_{on}$	Turn-on Switching Energy ⑥	<b>INDUCTIVE SWITCHING @ 125^\circ C</b> $V_{DD} = 133V, V_{GS} = 15V$ $I_D = 100A, R_G = 5\Omega$		935		
$E_{off}$	Turn-off Switching Energy			985		

**SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS**

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$I_S$	Continuous Source Current (Body Diode)			100	Amps
$I_{SM}$	Pulsed Source Current ① (Body Diode)			400	
$V_{SD}$	Diode Forward Voltage ② ( $V_{GS} = 0V, I_S = -100A$ )			1.3	Volts
$dv/dt$	Peak Diode Recovery $dv/dt$ ⑤			8	V/ns
$t_{rr}$	Reverse Recovery Time ( $I_S = -100A, di/dt = 100A/\mu s$ )	$T_j = 25^\circ C$		230	ns
		$T_j = 125^\circ C$		450	
$Q_{rr}$	Reverse Recovery Charge ( $I_S = -100A, di/dt = 100A/\mu s$ )	$T_j = 25^\circ C$		0.9	$\mu C$
		$T_j = 125^\circ C$		3.4	
$I_{RRM}$	Peak Recovery Current ( $I_S = -100A, di/dt = 100A/\mu s$ )	$T_j = 25^\circ C$		11	Amps
		$T_j = 125^\circ C$		20	

**THERMAL CHARACTERISTICS**

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.18	$^\circ C/W$
$R_{\theta JA}$	Junction to Ambient			40	

① Repetitive Rating: Pulse width limited by maximum junction temperature

② Pulse Test: Pulse width < 380  $\mu s$ , Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

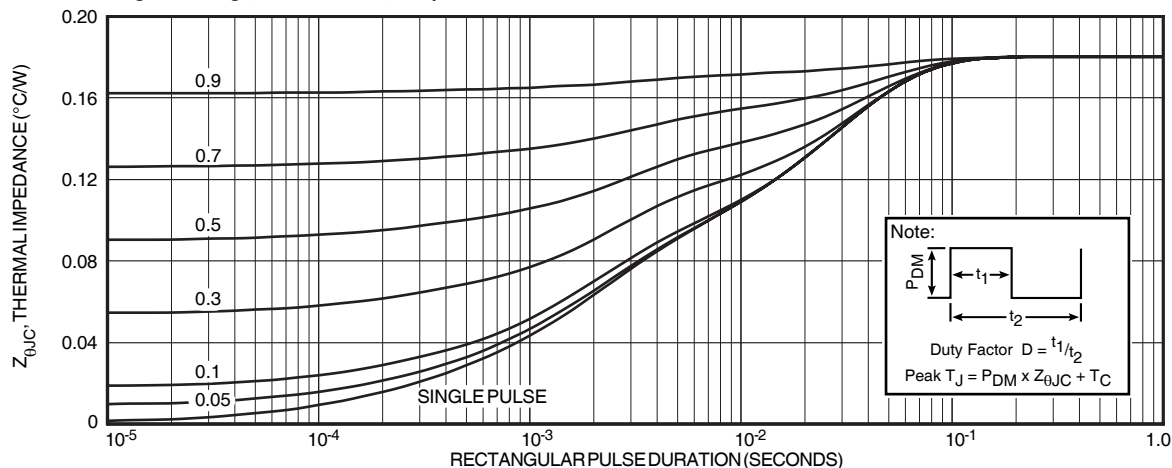
④ Starting  $T_j = +25^\circ C, L = 0.60mH, R_G = 25\Omega, \text{Peak } I_L = 100A$

⑤  $dv/dt$  numbers reflect the limitations of the test circuit rather than the device itself.  $I_S \leq -I_D 100A, di/dt \leq 700A/\mu s, V_R \leq 200V, T_j \leq 150^\circ C$

⑥  $E_{on}$  includes diode reverse recovery. See figures 18, 20.

⑦ The maximum current is limited by lead temperature

**APT Reserves the right to change, without notice, the specifications and information contained herein.**



**FIGURE 1, MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs PULSE DURATION**

# Typical Performance Curves

APT20M16B2FLL\_LFLL

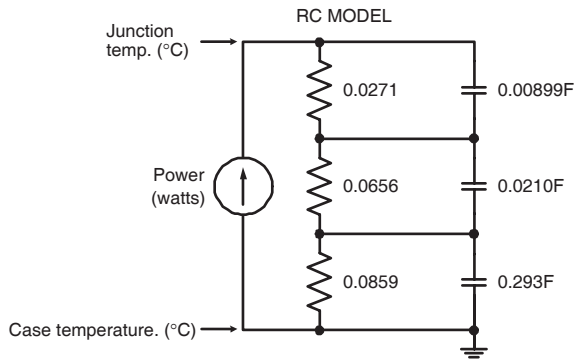


FIGURE 2, TRANSIENT THERMAL IMPEDANCE MODEL

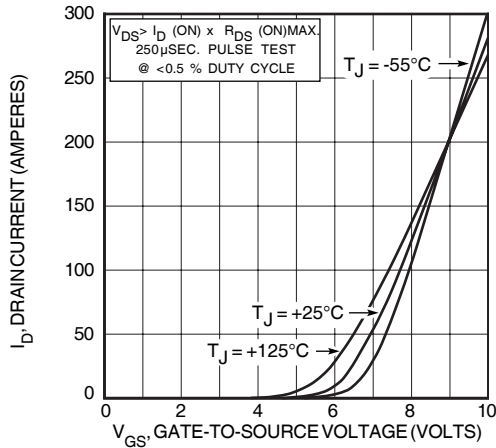


FIGURE 4, TRANSFER CHARACTERISTICS

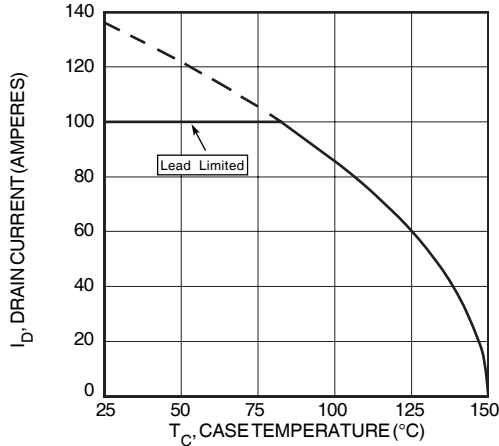


FIGURE 6, MAXIMUM DRAIN CURRENT vs CASE TEMPERATURE

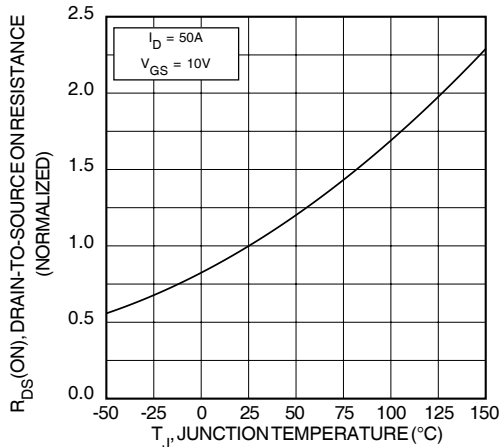


FIGURE 8, ON-RESISTANCE vs. TEMPERATURE

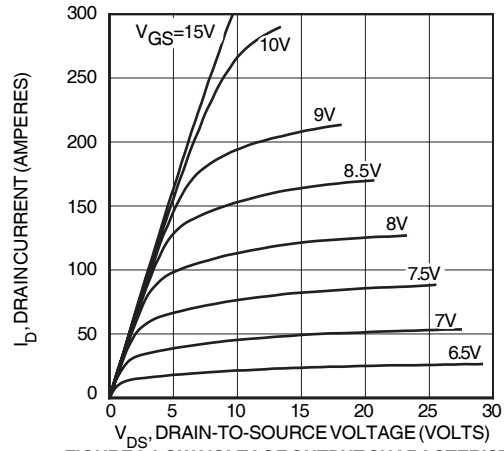


FIGURE 3, LOW VOLTAGE OUTPUT CHARACTERISTICS

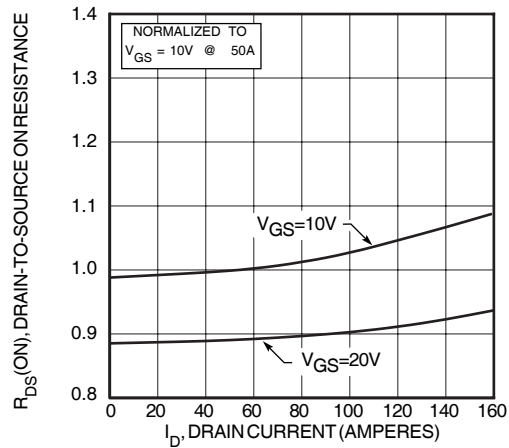


FIGURE 5,  $R_{DS(ON)}$  vs DRAIN CURRENT

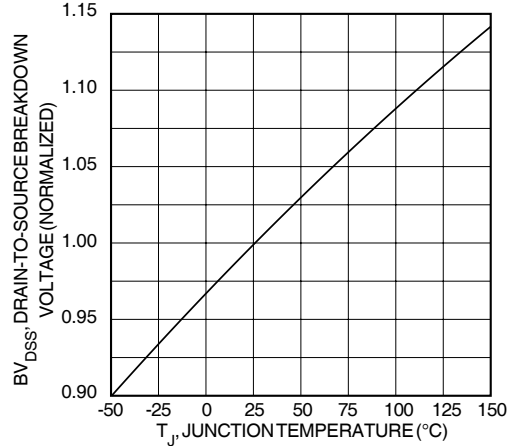


FIGURE 7, BREAKDOWN VOLTAGE vs TEMPERATURE

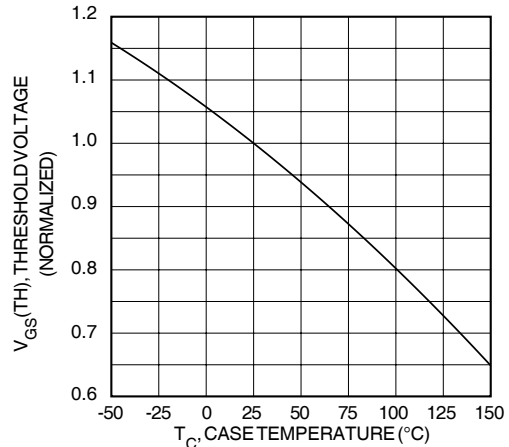


FIGURE 9, THRESHOLD VOLTAGE vs TEMPERATURE

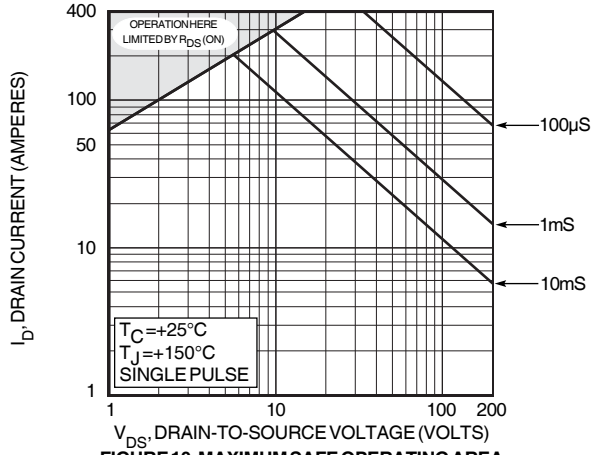


FIGURE 10, MAXIMUM SAFE OPERATING AREA

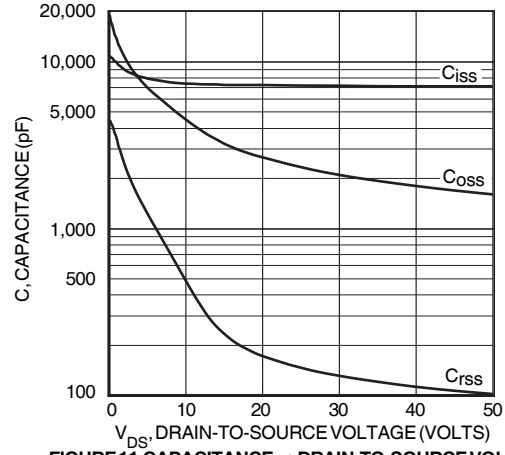


FIGURE 11, CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE

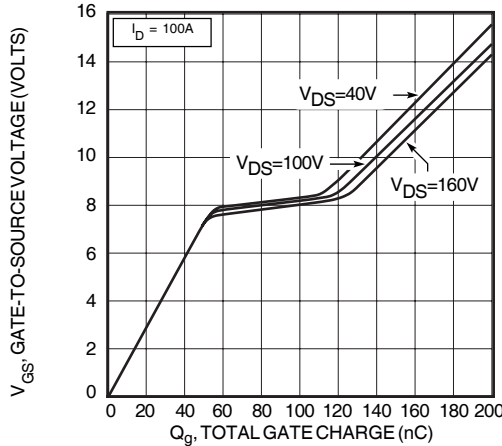


FIGURE 12, GATE CHARGES vs GATE-TO-SOURCE VOLTAGE

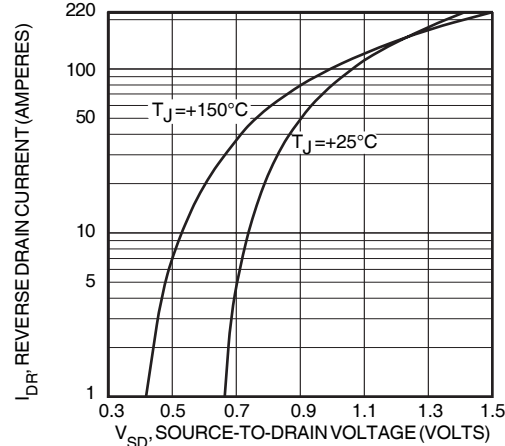


FIGURE 13, SOURCE-DRAIN DIODE FORWARD VOLTAGE

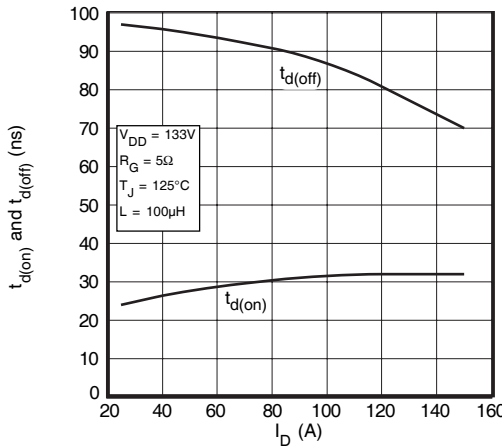


FIGURE 14, DELAY TIMES vs CURRENT

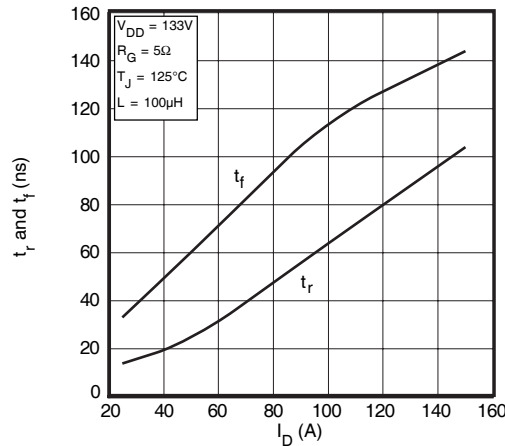


FIGURE 15, RISE AND FALL TIMES vs CURRENT

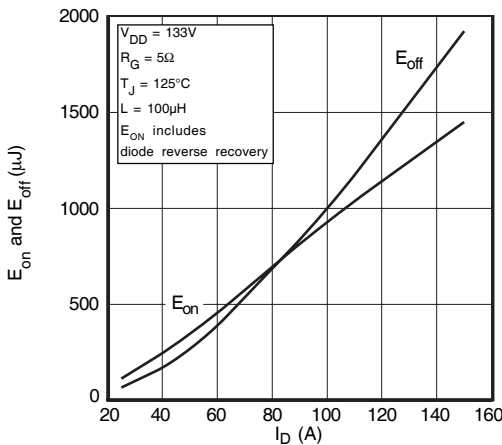


FIGURE 16, SWITCHING ENERGY vs CURRENT

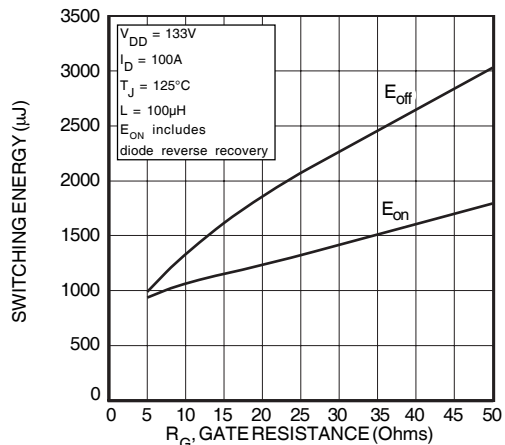


FIGURE 17, SWITCHING ENERGY vs. GATE RESISTANCE

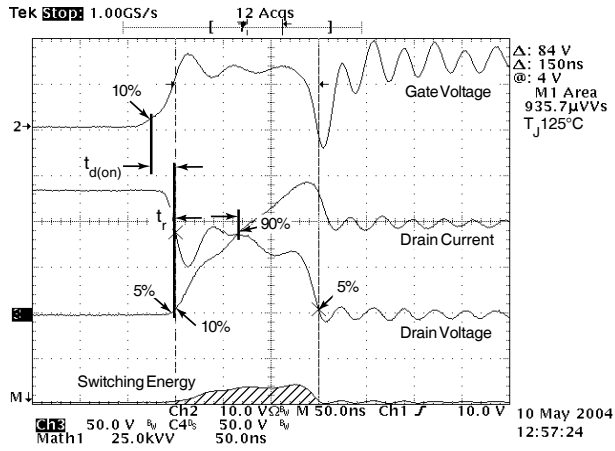


Figure 18, Turn-on Switching Waveforms and Definitions

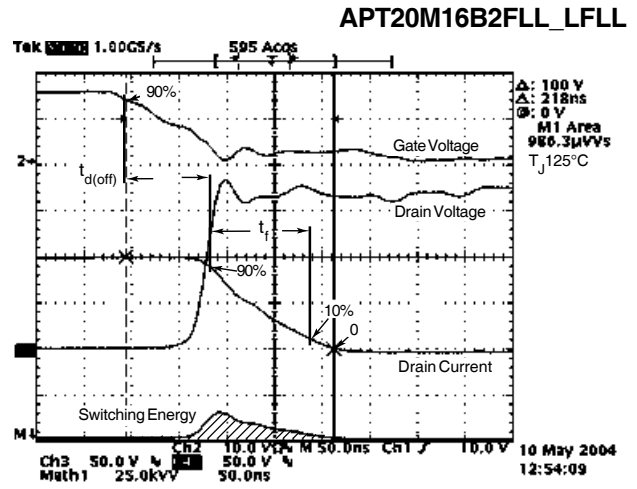


Figure 19, Turn-off Switching Waveforms and Definitions

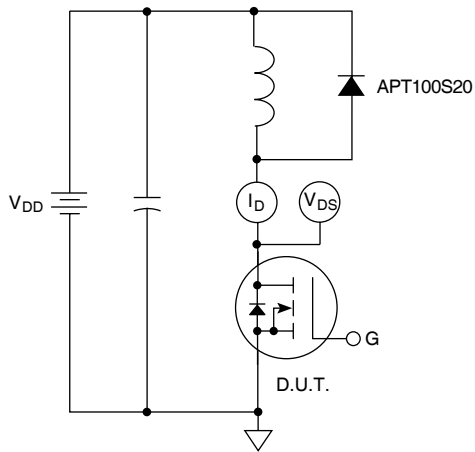
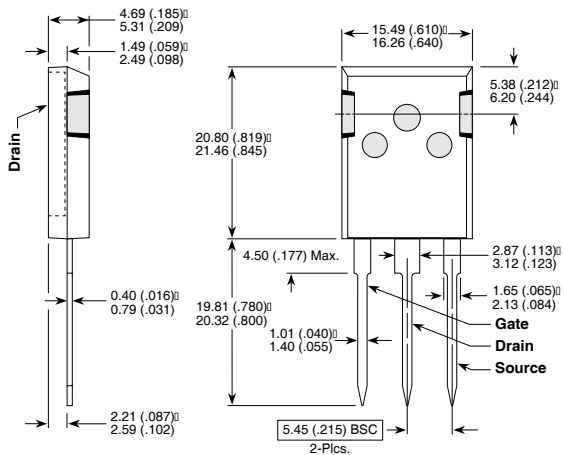


Figure 20, Inductive Switching Test Circuit

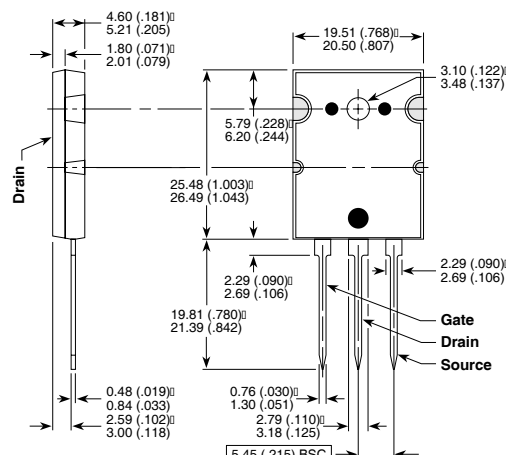
**T-MAX™ (B2) Package Outline (B2FLL)**



These dimensions are equal to the TO-247 without the mounting hole.

Dimensions in Millimeters and (Inches)

**TO-264 (L) Package Outline (LFLL)**



Dimensions in Millimeters and (Inches)

APT's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522

5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. US and Foreign patents pending. All Rights Reserved.

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[SSM6P69NU,LF](#) [DMP22D4UFO-7B](#)